

PCB Component Cooling

PTH PCB holes for maximum COOLING
Shipco Circuits Ltd 2013

Drill holes 0.5 mm (finished approx. 0.4 mm). Swap X&Y in example as required.

Drill first a row of holes in X with pitch 0.7 mm, not less to obtain minimum 0.2 mm substrate between holes.

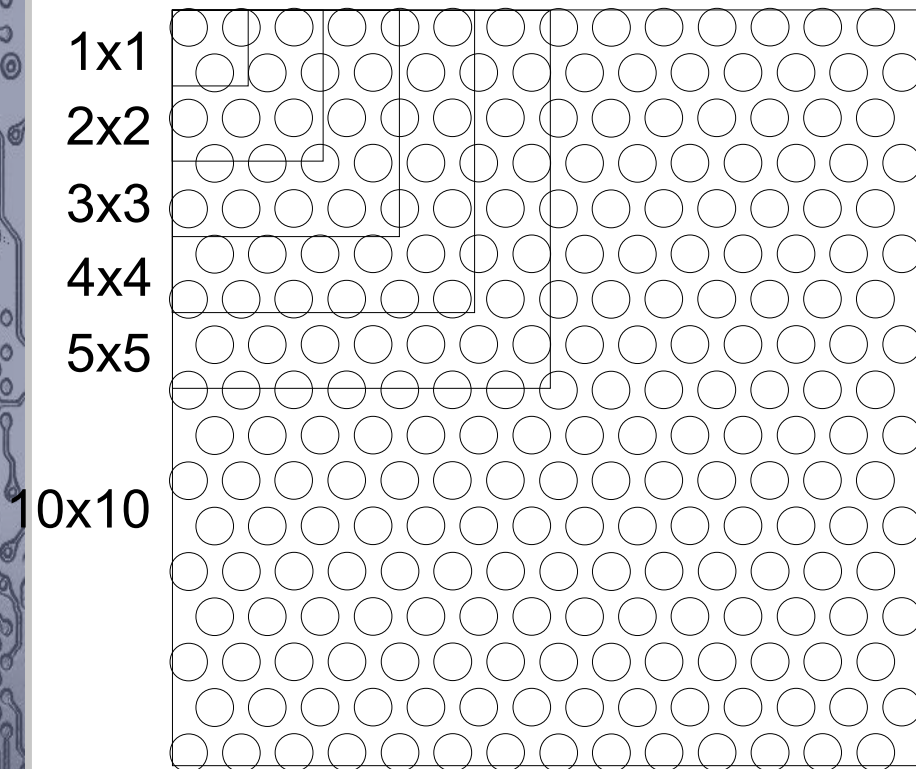
Then drill 2nd row like the first but offset 0.6 mm in Y and offset half the X-pitch in X, and drill one hole less than first row.







Then repeat above with pitch 1.2 mm in Y as many times as required.

Copper plate holes 0.25 mm min, more if feasible but not less!

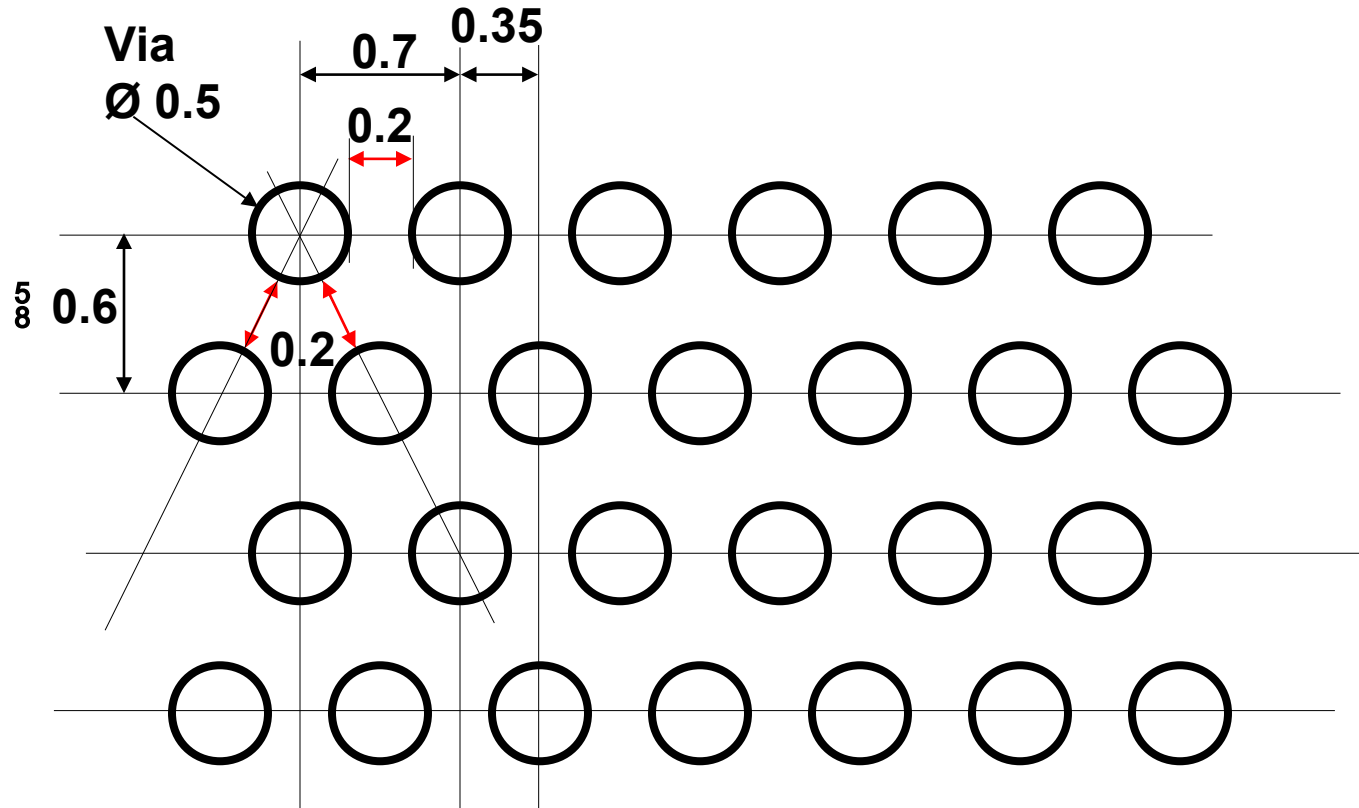
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Viahål: Ø 0.5, Cu area/via= 0.03731
Min distans alla riktningar: 0.2



10x10mm ²		= 238 via, A=8.88mm ²
5x5mm ²		= 56 via, A=2.09
4x4mm ²		= 39 via, A=1.46
3x3mm ²		= 20 via, A=0.75
2x2mm ²		= 8 via, A=0.3
1x1mm ²		= 2 via, A=0.075

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Solder mask stop in via holes, $\text{Ø } 0.5$

